

**NCCAUS Joint User Group Meeting Agenda (CMPUG, PAG, & TFUG)
Novel Applications of Advanced Semiconductor Device Packaging Technology**

Meeting Date: Thursday, June 24, 2021

Time: 12:45 p.m.-3:30 p.m. PDT ([TIME ZONE CONVERTER](#))

Co-Chairs:

Rob Rhoades, Revasum, rob.rhoades@revasum.com

Jeff Shields, Adesto Technology, jeffrey.shields@att.net

Paul Werbaneth, Ichor Systems, pfwerbaneth@gmail.com

AGENDA

12:45 p.m. Welcome and Acknowledgement of Meeting Sponsors, Joint User Group Meeting
Co-Chairs Rob Rhoades, Jeff Shields, Paul Werbaneth

1:00 p.m. **David Lishan**, Ph.D., Plasma-Therm, *Higher Yield, Lower Cost Power Devices Through Plasma Dicing Process Integration*

1:30 p.m. **Joseph Suttle**, Ph.D., IBM Quantum, *Advanced Packaging for Superconducting Quantum Processors*

2:00 p.m. **Alissa Fitzgerald**, Ph.D., A.M. Fitzgerald & Associates, *MEMS: Strategies for Codevelopment of the Electronics and the Package*

2:30 p.m. **Matt Francis**, Ozark Integrated Circuits, *Unique Electronic Device Packaging Solutions for Rugged Environments*

3:00 p.m. **Debbie Senesky**, Professor, Stanford University, *Packaging of Micro- and Nano-Systems for Operation within Extreme Harsh Environments*

3:30 p.m. ADJOURN